L Number	Hits	Search Text	DB	Time stamp
-	226	(438/458).CCLS.	USPAT;	2002/03/06
l .			US-PGPUB	11:21
-	446897	bond or bonding or bonded	USPAT;	2002/03/07
			US-PGPUB	14:35
-	178	((438/458).CCLS.) and (bond or bonding or bonded)	USPAT;	2002/03/06
ļ			US-PGPUB USPAT;	11:23 2002/03/07
-	18697	delaminat\$	US-PGPUB	14:35
		(((0 / 0) COLC) and (hand on handing or handed)) and	USPAT;	2002/03/06
-	16	(((438/458).CCLS.) and (bond or bonding or bonded)) and	US-PGPUB	11:31
	00.4	delaminat\$	USPAT;	2002/03/06
-	234	438/406.ccls.	US-PGPUB	11:31
_	189	(bond or bonding or bonded) and 438/406.ccls.	USPAT:	2002/03/06
-	109	(bold of bolding of bolided) and 430/400/0000	US-PGPUB	11:31
_	8	delaminat\$ and ((bond or bonding or bonded) and	USPAT;	2002/03/06
	J	438/406.ccls.)	US-PGPUB	11:33
_	39	438/506.ccls.	USPAT;	2002/03/06
	39	400/300100101	US-PGPUB	11:34
_	1	delaminat\$ and 438/506.ccls.	USPAT;	2002/03/06
		10 70	US-PGPUB	11:34
_	3	(bond or bonding or bonded) and 438/506.ccls.	· USPAT;	2002/03/06
	Ü		US-PGPUB	11:34
-	36	438/506.ccls. not ((bond or bonding or bonded) and	USPAT;	2002/03/06
ļ		438/506.ccls.)	US-PGPUB	11:35
-	1464	"micro bubble" or microbubbles	USPAT;	2002/03/06
			US-PGPUB	11:47
, -	0	438/506.ccls. and ("micro bubble" or microbubbles)	USPAT;	2002/03/06
İ			US-PGPUB	11:36
-	5648	implant\$ with wafer	USPAT;	2002/03/06
			US-PGPUB	11:36
-	9	438/506.ccls. and (implant\$ with wafer)	USPAT;	2002/03/06
-			US-PGPUB	11:37
	203	438/514.ccls.	USPAT; US-PGPUB	2002/03/06 11:38
		11 to the 1/4 to the line as bonded) and	USPAT;	2002/03/06
-	О	delaminat\$ and ((bond or bonding or bonded) and	US-PGPUB	11:38
		438/514.ccls.)	USPAT;	2002/03/06
-	30	(bond or bonding or bonded) and 438/514.ccls.	US-PGPUB	11:40
	110	438/for.365.ccls.	EPO; JPO;	12002/03/06
-	112	430/101.305.ccis.	DERWENT	11:40
	553582	bond or bonding or bonded	EPO; JPO;	2002/03/06
-	553502	bolid of boliding of bolided	DERWENT	11:41
_	8984	delaminat\$	EPO; JPO;	2002/03/06
	0904		DERWENT	11:41
_	0	delaminat\$ and (438/for.365.ccls. and (bond or bonding or	EPO; JPO;	2002/03/06
	Ū	bonded))	DERWENT	11:41
_	40		EPO; JPO;	1 2002/03/06
	7-	404/0	DERWENT	11:42
_	o	438/for.365.ccls. and delaminat\$	EPO; JPO;	2002/03/06
		43-73-0	DERWENT	11:43
-	368	438/for.386.ccls.	PPO; JPO;	2002/03/06
	J		' DERWENT	11:43
_	0	delaminat\$ and ((bond or bonding or bonded) and	EPO; JPO;	2002/03/06
		438/for.386.ccls.)	DERWENT	11:43
-	О	delaminat\$ and 438/for.386.ccls.	EPO; JPO;	2002/03/00
			DERWENT	11:43
	51	(bond or bonding or bonded) and 438/for.386.ccls.	EPO; JPO;	2002/03/0
			DERWENT	11:44
-	135	438/for.403.ccls.	EPO; JPO;	2002/03/0
			DERWENT	11:45
-	9	(bond or bonding or bonded) and 438/for.403.ccls.	EPO; JPO;	2002/03/0
			DERWENT	11:46
-	141	438/for.408.ccls.	EPO; JPO;	2002/03/00
1	1		DERWENT	11:46

-	0	delaminat\$ and 438/for.408.ccls.	EPO; JPO;	2002/03/06
			DERWENT	11:46
_	6	(bond or bonding or bonded) and 438/for.408.ccls.	EPO; JPO;	2002/03/06
			DERWENT	. 11:47
-	1912	(bond or bonding or bonded) and delaminat\$	EPO; JPO;	2002/03/06
			DERWENT	11:47
-	901	"micro bubble" or microbubbles	EPO; JPO;	2002/03/06
			DERWENT	11:48
-	1	((bond or bonding or bonded) and delaminat\$) and ("micro	EPO; JPO;	2002/03/06
		bubble" or microbubbles)	DERWENT	11:48
-	6085	SOI	EPO; JPO;	2002/03/06
			DERWENT	11:51
-	6	((bond or bonding or bonded) and delaminat\$) and SOI	EPO; JPO;	2002/03/06
	1		DERWENT	11:48
-	5779	SOI	USPAT;	2002/03/06
			US-PGPUB	11:52
-	62	(bond or bonding or bonded) and delaminat\$ and SOI	USPAT;	2002/03/07
	Ì .		US-PGPUB	14:35 2002/03/07
-	8984	delaminat\$	EPO; JPO;	
	_		DERWENT	14:38 2002/03/07
-	553582	bond or bonding or bonded	EPO; JPO; DERWENT	
				14:38 2002/03/07
-	17	"smart cut"	EPO; JPO; DERWENT	14:38
		0/5	EPO; JPO;	2002/03/07
-	389	438/for.158.ccls.	DERWENT	14:36
		0.0000000000000000000000000000000000000	EPO; JPO;	2002/03/07
-	111	438/for.485.ccls.	DERWENT	14:37
		0 /mo0 ools	USPAT;	2002/03/07
-	229	438/528.ccls.	US-PGPUB	14:37
	110	438/977.ccls.	USPAT;	2002/03/07
-	440	430/9//.ccis.	US-PGPUB	14:37
	044	148/dig.12.ccls.	USPAT;	2002/03/07
-	244	140/uig.12.ccis.	US-PGPUB	14:38
	18720	delaminat\$	USPAT:	2002/03/07
_	16/20	Qelailillaτφ	US-PGPUB	14:38
	447475	bond or bonding or bonded	USPAT;	2002/03/07
-	447475	bond of bonding of bonded	US-PGPUB	14:39
	80	"smart cut"	USPAT;	2002/03/07
1		Smart cut	US-PGPUB	14:39
_	12	148/dig.12.ccls. and delaminat\$ and (bond or bonding or	USPAT;	2002/03/07
-	13	bonded)	US-PGPUB	14:40
1_	2921	batch with furnace	USPAT;	2002/03/07
-	2921	Dutch min turnuce	US-PGPUB	14:41
1_	31	delaminat\$ and (batch with furnace)	USPAT;	2002/03/07
1-	31	actuality and (Sucon the tartings)	US-PGPUB	14:43
_	15	(bond or bonding or bonded) and (delaminat\$ and (batch with	USPAT;	2002/03/07
	13	furnace))	US-PGPUB	14:43
L		1		